CNY17-X Series

Rev.A.1.0

DESCRIPTION:

The CNY17-X series combine an AIGaAs infrared emitting diode as the emitter which is optically coupled to a silicon

Characteristics Curves

FIG.1: Forward Current vs. Ambient Temperature

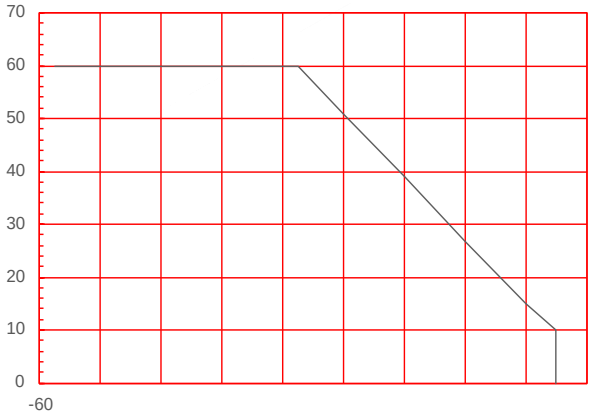


FIG.2: Collector Power Dissiption vs. Ambient Temperature

FIG.7: Normalized Current Transfer Ratio vs. Ambient Temperature

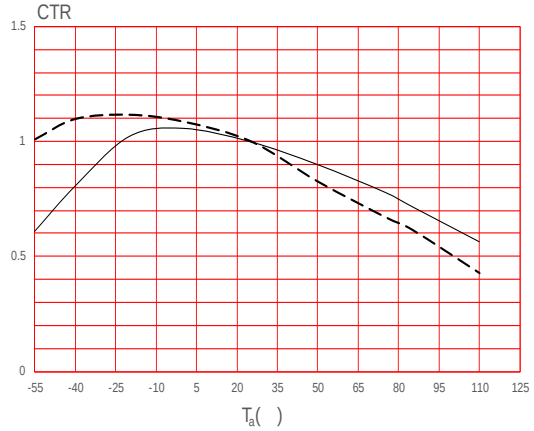


FIG.8: Normalized Collector-emitter Saturation Voltage vs. Ambient Temperature 1105031 m 99-0.0f*4.9

Test Circuits

FIG.13: Test Circuits of Response Time

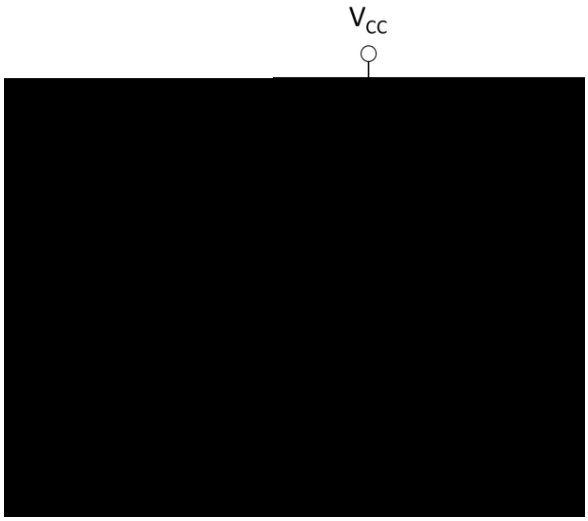
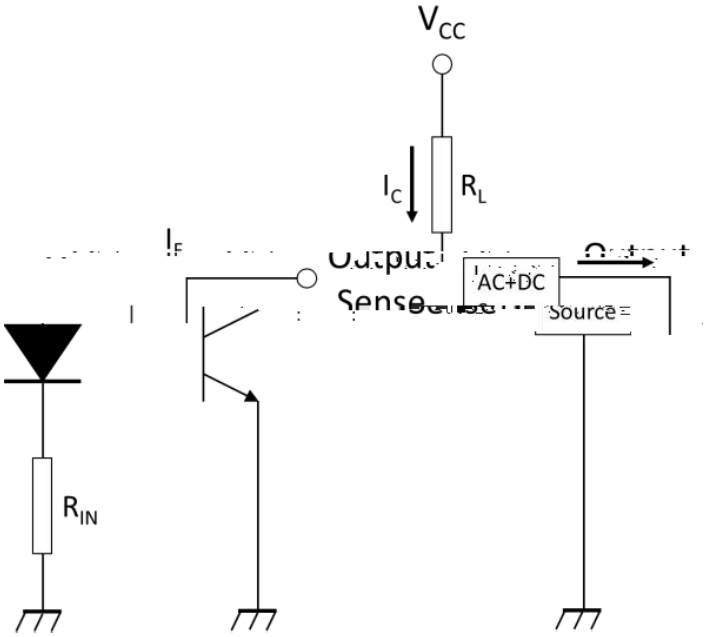


FIG.14: Curves of Response Time

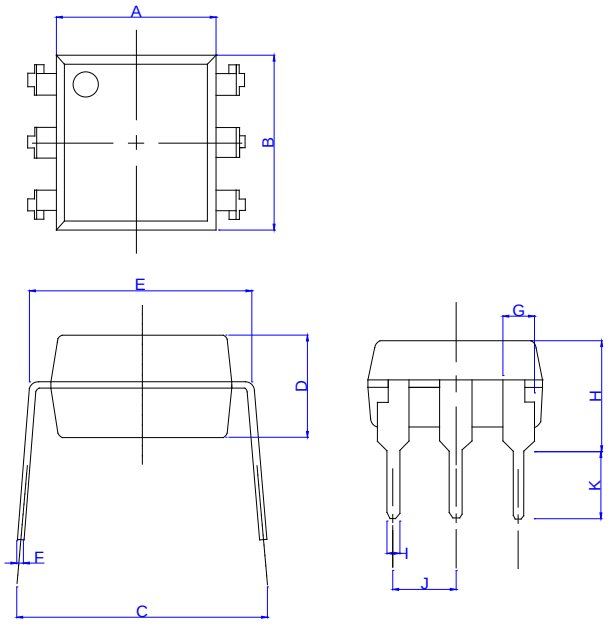


FIG.15: Test Circuits of Frequency Response



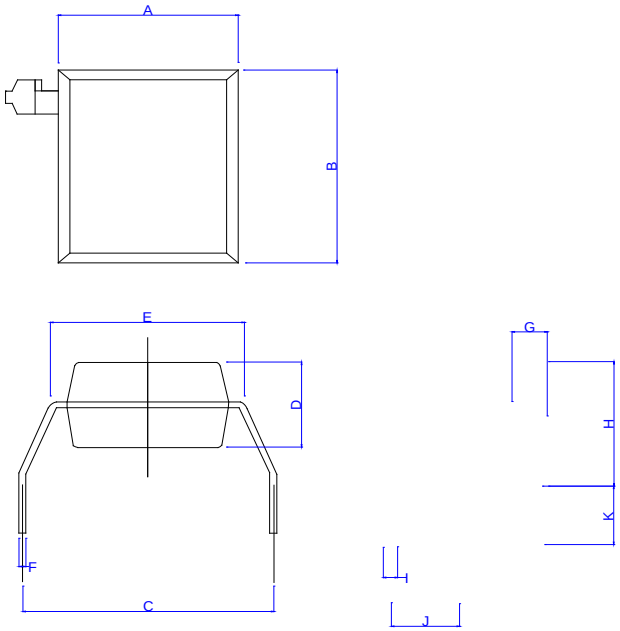
Package Dimension (Unit: mm)

Standard DIP Type:



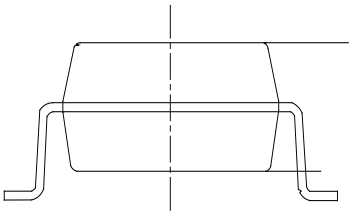
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.00		7.00	0.237		0.277
B	6.62		7.62	0.262		0.301
C	7.10		10.16	0.281		0.402
D	3.00		4.00	0.119		0.158
E	7.32		7.92	0.289		0.313
F	0.16		0.36	0.006		0.014
G	0.90		1.50	0.036		0.059
H	3.50		4.80	0.138		0.190
I	0.40		0.60	0.016		0.024
J	2.29		2.79	0.091		0.110
K	2.40		3.40	0.095		0.134

Option M Type:



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.00		7.00	0.237		0.277
B	6.82		7.42	0.270		0.293
C	9.66		10.66	0.382		0.421
D	3.00		4.00	0.119		0.158
E	7.32		7.92	0.289		0.313
F						
G	0.90		1.50	0.036		0.059
H	4.28		4.88	0.169		0.193
I						
J						
K						

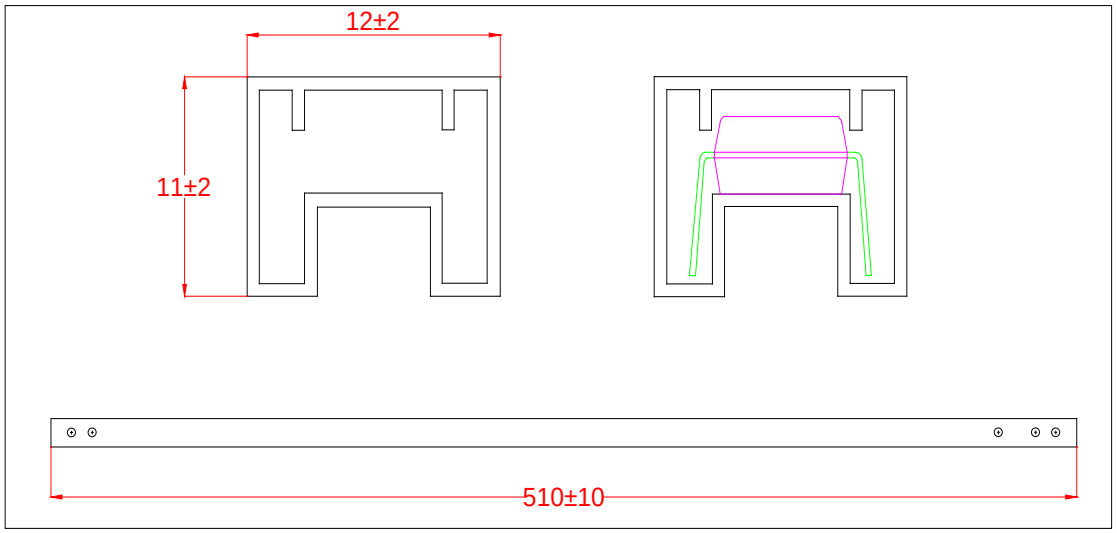
Option S Type:



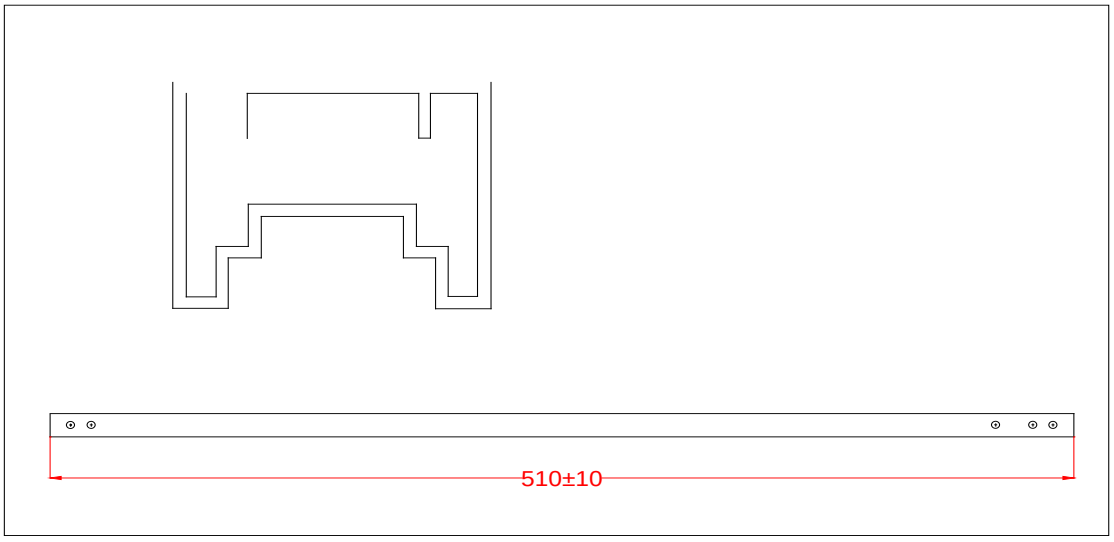
RECOMMENDED SOLDER MASK

TUBE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

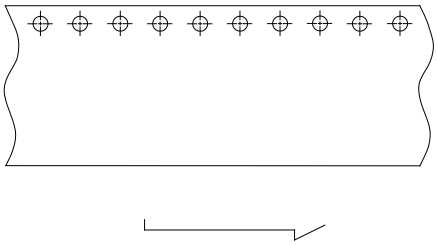
Standard DIP



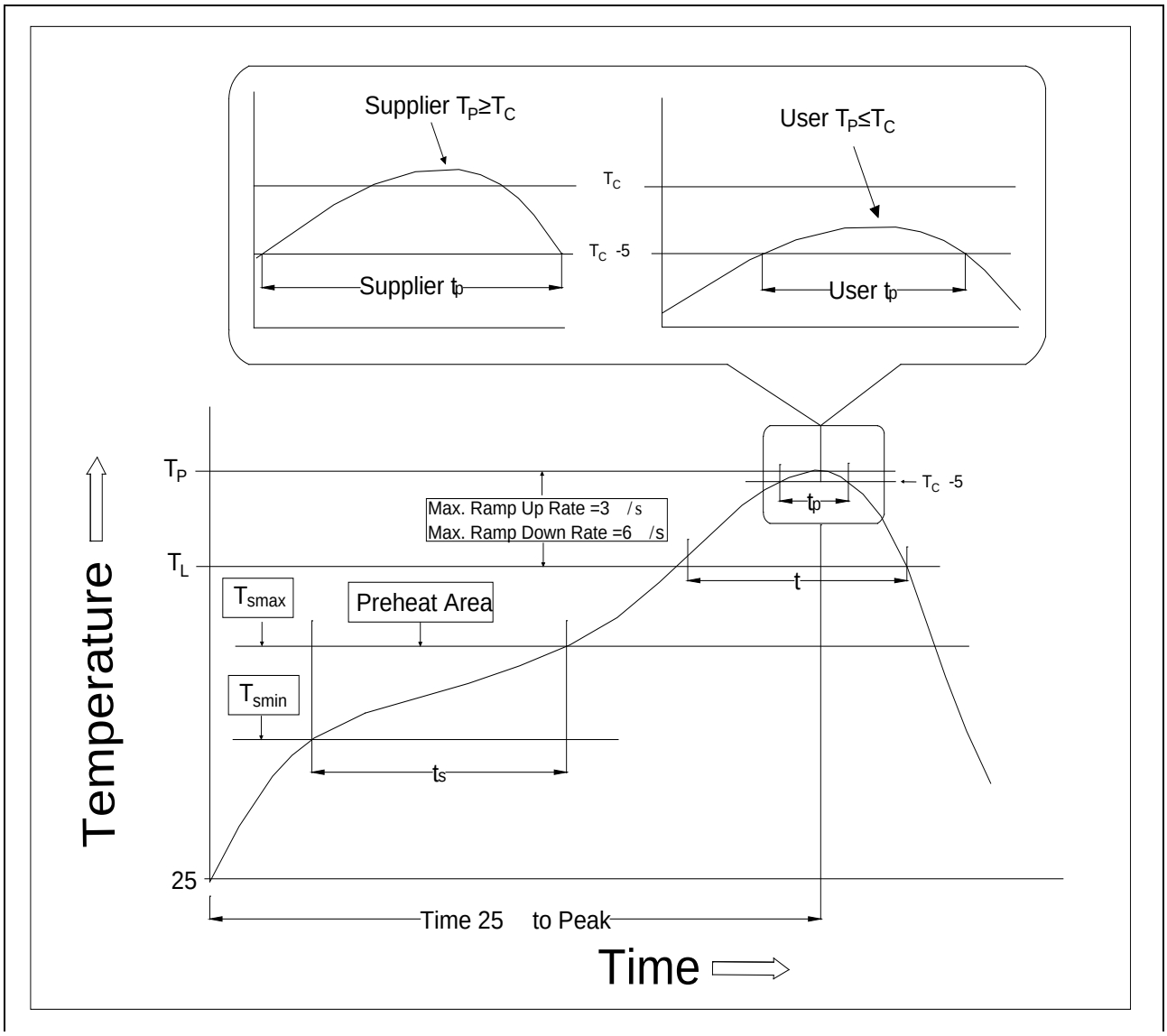
Option M



CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)



REFLOW INFORMATION



P

WAVE SOLDERING



HAND SOLDERING BY SOLDERING IRON	
Soldering Temperature	360 5
Soldering Time	3s max.

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.

2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.

3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.

4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent